

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMC6061AIM/NOPB	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 85	LMC60 61AIM
LMC6061AIMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	(6061AI, LMC60) 61AIM
LMC6061AIMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(6061AI, LMC60) 61AIM
LMC6061AIMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(6061AI, LMC60) 61AIM
LMC6061IM/NOPB	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 85	LMC60 61IM
LMC6061IMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 61IM
LMC6061IMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 61IM
LMC6061IMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 61IM
LMC6062AIM/NOPB	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 85	LMC60 62AIM
LMC6062AIMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62AIM
LMC6062AIMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62AIM
LMC6062AIMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62AIM
LMC6062I MDC	Active	Production	DIESALE (Y) 0	288 OTHER	Yes	Call TI	Level-1-NA-UNLIM	-40 to 85	
LMC6062I-MDC.A	Active	Production	DIESALE (Y) 0	288 OTHER	Yes	Call TI	Level-1-NA-UNLIM	-40 to 85	
LMC6062IM/NOPB	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 85	LMC60 62IM
LMC6062IMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62IM
LMC6062IMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62IM

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LMC6062IMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62IM
LMC6062IN/NOPB	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	LMC6062 IN
LMC6062IN/NOPB.A	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	LMC6062 IN
LMC6062IN/NOPB.B	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	LMC6062 IN
LMC6064AIM/NOPB	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-40 to 85	LMC6064 AIM
LMC6064AIMX/NOPB	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6064 AIM
LMC6064AIMX/NOPB.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6064 AIM
LMC6064IM/NOPB	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-40 to 85	LMC6064IM
LMC6064IMX/NOPB	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6064IM
LMC6064IMX/NOPB.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6064IM

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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